

AMENDMENTS TO THE CLAIMS

Listing of claims:

This listing of claims replaces all prior versions and listings of claims in the application.

Claim 1 (Previously Presented): A test apparatus used for testing a multilayer wiring board being fabricated by stacking wiring layers successively, said test apparatus comprising:

- a probe that detects defects in the multilayer wiring board under fabrication ; and
- an element supplementing unit that mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe.

Claim 2 (Previously Presented): The test apparatus as claimed in claim 1, wherein the additional elements to be mounted are included in the element supplementing unit.

Claim 3 (Previously Presented): The test apparatus as claimed in claim 1, wherein the element supplementing unit includes

- a first section arranged to face a first side of the multilayer wiring board under fabrication to mount the additional elements on the first side; and

- a second section arranged to face a second side of the multilayer wiring board under fabrication to mount the additional elements on the second side.

Claim 4 (Withdrawn): A method of fabricating a multilayer wiring board, comprising:

- a first step of testing the multilayer wiring board under fabrication to detect whether defects exist;
- a second step of mounting additional elements on the multilayer wiring board under fabrication when no defect is detected;
- a third step of testing the multilayer wiring board including the additionally mounted elements; and
- a fourth step of continuing or stopping mounting of further additional elements according to testing results of the third step.

Claim 5 (Withdrawn): The method as claimed in claim 4, wherein a test apparatus is provided to test the multilayer wiring board under fabrication and to mount the additional elements, said test apparatus comprising a probe for testing and an element supplementing unit for mounting the additional elements.

Claim 6 (Withdrawn): The method as claimed in claim 5, wherein the additional elements to be mounted are carried by the element supplementing unit.

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Claim 7 (Withdrawn): The method as claimed in claim 4, wherein testing and mounting of the additional elements are performed on opposite two sides of the multilayer wiring board under fabrication.

Claim 8 (New): The test apparatus as claimed in claim 1, wherein when a defect is detected by the probe in the multilayer wiring board under fabrication, the element supplementing unit disposes of the multilayer wiring board.